The MM70 series is a graphics board connector compatible with the MXM3.0 standard. It can be used to connect add-in MXM3.0 modules (graphics boards) in order to improve the graphics processing performance of personal computers.

**Features**

- Mating area is 0.5mm pitch, with two-layer upper and lower structure.
- Compatible with MXM3.0 standard. (Card edge type).
- Contact size: available in 2 types
  - 6.7mm height, 12.20mm depth, and 89.9mm width. (3.0mm board height)
  - 4.3mm height, 12.75mm depth, and 89.9mm width. (1.5mm board height)
- Precision positioning stopper for MXM3.0 module prevents contact failure.

**General Specifications**

- No. of Contacts: 314 pos. equivalent (310 pos.)
- Contact Resistance: 55m Ω max. (initial), 80m Ω max. (after test)
- Dielectric Withstanding Voltage: AC 250Vr.m.s (per minute)
- Rated Current: 0.5A per pin
- Insulation Resistance: 50M Ω min. (after test)
- Durability: 30 times
- Operating Temperature: -40 to+85 Deg. C
**Materials and Finishes**

<table>
<thead>
<tr>
<th>Component</th>
<th>Material / Finish</th>
</tr>
</thead>
<tbody>
<tr>
<td>Insulator</td>
<td>Heat resistant plastic</td>
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<tr>
<td>Contact</td>
<td>Copper alloy / contact area: 0.1µm min. Au plating over Ni</td>
</tr>
<tr>
<td>Hold down</td>
<td>Copper alloy / Sn plating over Ni</td>
</tr>
<tr>
<td>Stopper</td>
<td>Copper alloy / Sn plating over Ni</td>
</tr>
</tbody>
</table>

**Ordering Information**

**MM70- 314 - 310 B 2 - ***

- **Contact finish**
  1: 0.1µm min. Au plating over Ni
  2: 0.3µm min. Au plating over Ni

- **Modification code**
  1. Board height: 3.0mm
  2. Board height: 1.5mm

- **Socket type, angle insertion type**

- **Utilized No. of Contacts**

- **Standard No. of Contacts**

**Drawing No.**

<table>
<thead>
<tr>
<th>Part Number</th>
<th>SJ Drawing</th>
<th>Specification</th>
</tr>
</thead>
<tbody>
<tr>
<td>MM70-314-310B2-1</td>
<td>SJ109148</td>
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<td>MM70-314-310B2-2</td>
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<td>JACS-10543</td>
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<td>MM70-314-310B1-1</td>
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<td>MM70-314-310B1-2</td>
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</tbody>
</table>
Applicable dimensions of module board (for reference)

Notice: Products shown in this leaflet are made for the applications listed below. However, if the above-mentioned products are to be used in aerospace devices, marine cable-connection devices, atomic power control systems, medical equipment for life-support systems, or any other specific application requiring extremely high reliability, please contact JAE for further information.

Recommended applications: Computers, Office machines, Measuring devices, Telecommunication devices (Terminals, Mobile devices), AV devices, Household applications, FA devices, etc.

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* The specifications in this brochure are subject to change without notice. Please contact JAE for information.